

# EGFM301-BS THRU EGFM305-BS

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# EGFM301-BS THRU EGFM305-BS

## 3.0A Surface Mount Efficient Fast Rectifiers-50-600V

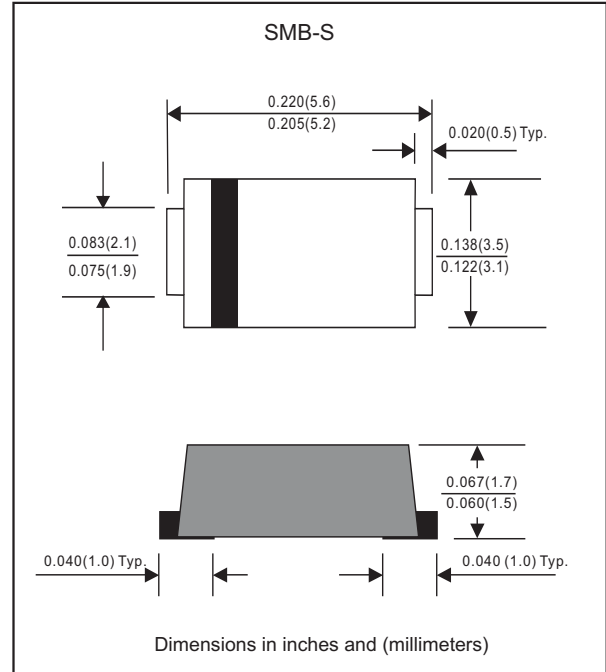
### Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance.
- Low profile surface mounted application in order to optimize board space.
- High current & surge capability.
- Low forward drop voltage
- Glass passivated chip junction.
- Lead-free parts meet environmental standards of MIL-STD-19500 /228
- Suffix "-H" indicates Halogen free parts, ex. EGFM301-BS-H.

### Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, DO-214AA/SMB-S
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.072 gram

### Package outline



### Maximum ratings and Electrical Characteristics (AT T<sub>A</sub>=25°C unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.2	I <sub>o</sub>			3.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I <sub>FSM</sub>			100	A
Reverse current	V <sub>R</sub> = V <sub>RRM</sub> T <sub>J</sub> = 25°C	I <sub>R</sub>			5.0	uA
	V <sub>R</sub> = V <sub>RRM</sub> T <sub>J</sub> = 125°C				100	
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C <sub>J</sub>		50		pF
Storage temperature		T <sub>STG</sub>	-65		+175	°C

SYMBOLS	V <sub>RRM</sub> <sup>*1</sup> (V)	V <sub>RMS</sub> <sup>*2</sup> (V)	V <sub>R</sub> <sup>*3</sup> (V)	V <sub>F</sub> <sup>*4</sup> (V)	t <sub>rr</sub> <sup>*5</sup> (ns)	Operating temperature T <sub>J</sub> , (°C)
EGFM301-BS	50	35	50	0.875	25	-55 to +150
EGFM302-BS	100	70	100			
EGFM303-BS	200	140	200			
EGFM304-BS	400	280	400	1.25		
EGFM305-BS	600	420	600	1.75		

- \*1 Repetitive peak reverse voltage
- \*2 RMS voltage
- \*3 Continuous reverse voltage
- \*4 Maximum forward voltage@I<sub>F</sub>=3.0A
- \*5 Maximum Reverse recovery time, note 1

Note 1. Reverse recovery time test condition, I<sub>F</sub>=0.5A, I<sub>R</sub>=1.0A, I<sub>RR</sub>=0.25A

# Rating and characteristic curves (EGFM301-BS THRU EGFM305-BS)

FIG.1-TYPICAL FORWARD CHARACTERISTICS

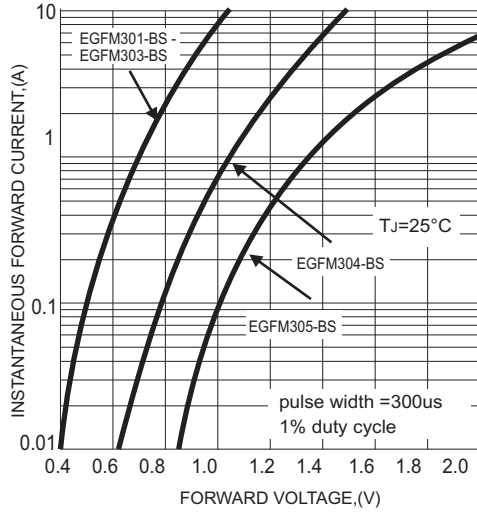


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

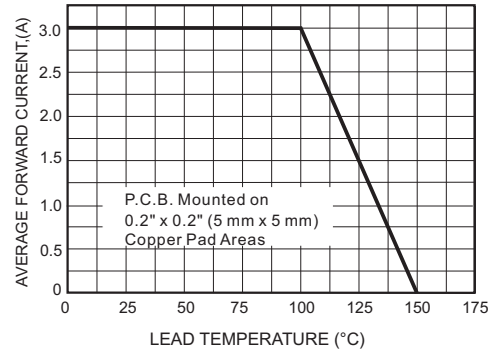
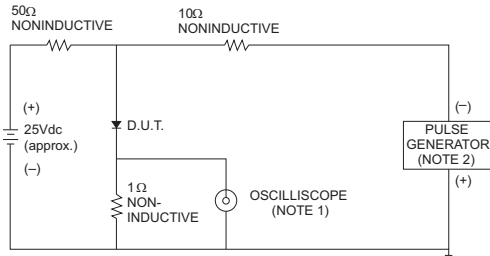


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



- NOTES: 1. Rise Time = 7ns max., Input Impedance = 1 megohm, 22pF.  
2. Rise Time = 10ns max., Source Impedance = 50 ohms.

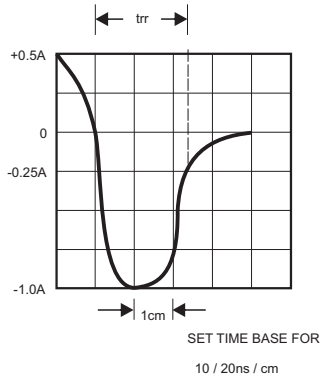


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

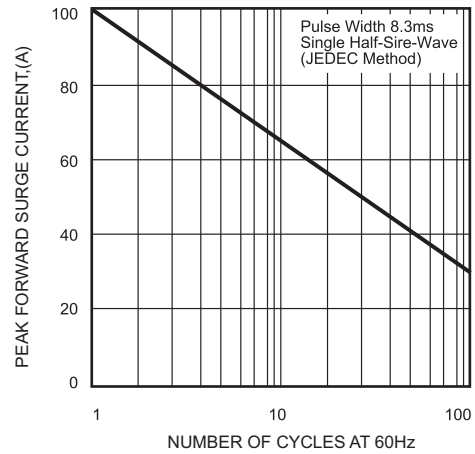
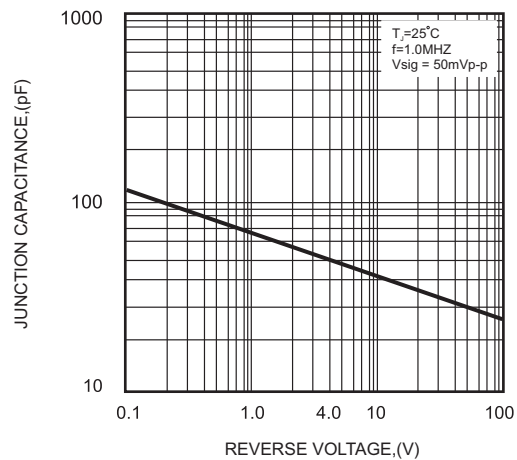




FIG.5-TYPICAL JUNCTION CAPACITANCE



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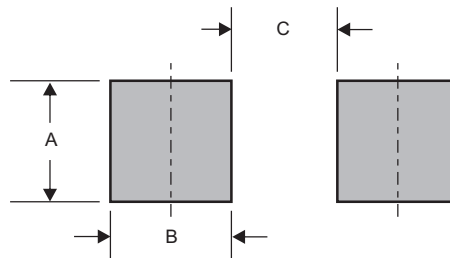
## Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

## Marking

Type number	Marking code
EGFM301-BS	E31
EGFM302-BS	E32
EGFM303-BS	E33
EGFM304-BS	E34
EGFM305-BS	E35

## Suggested solder pad layout

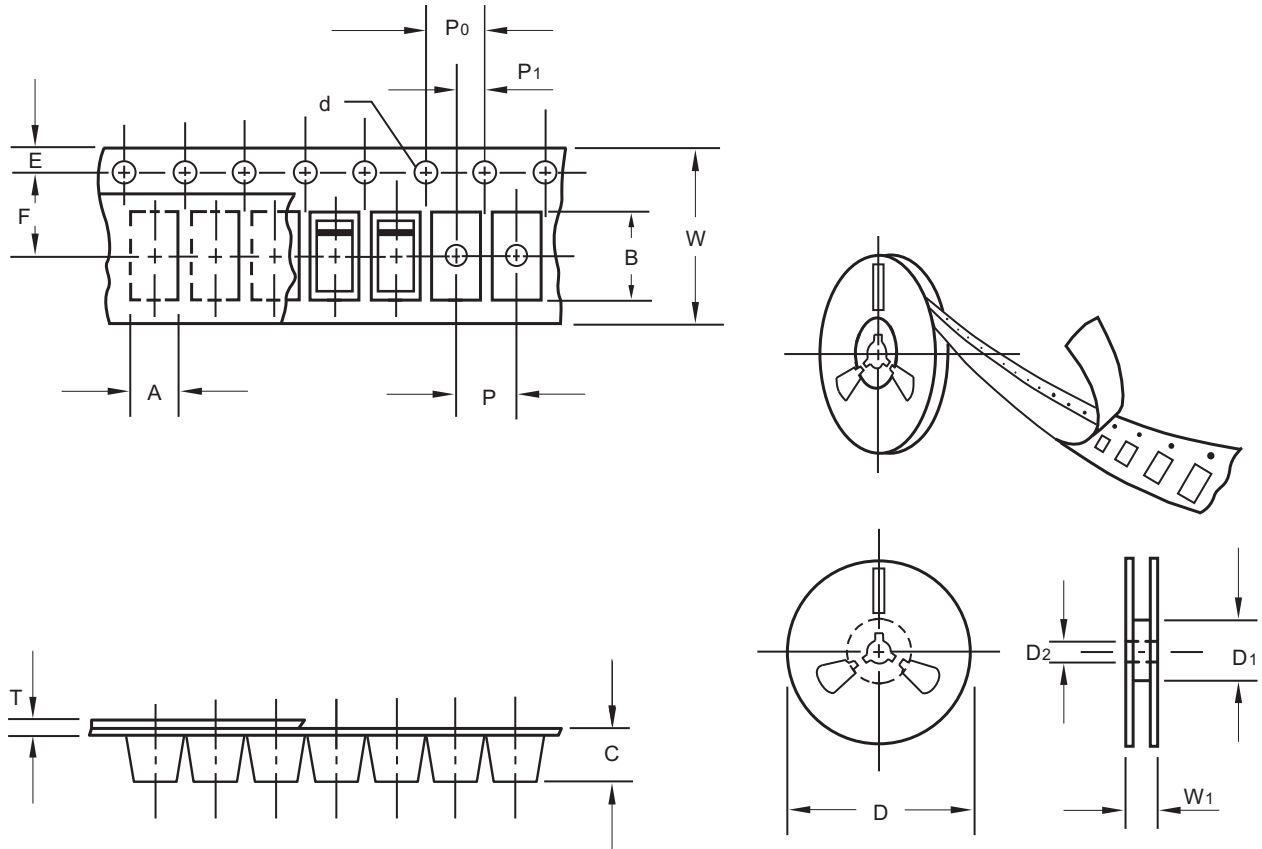


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMB-S	0.078 (2.00)	0.059 (1.50)	0.110 (2.80)

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## Packing information



unit:mm

Item	Symbol	Tolerance	SMB-S
Carrier width	A	0.1	3.81
Carrier length	B	0.1	5.74
Carrier depth	C	0.1	2.24
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D1	min	50.00
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	62.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	12.00
Reel width	W1	1.0	18.00

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

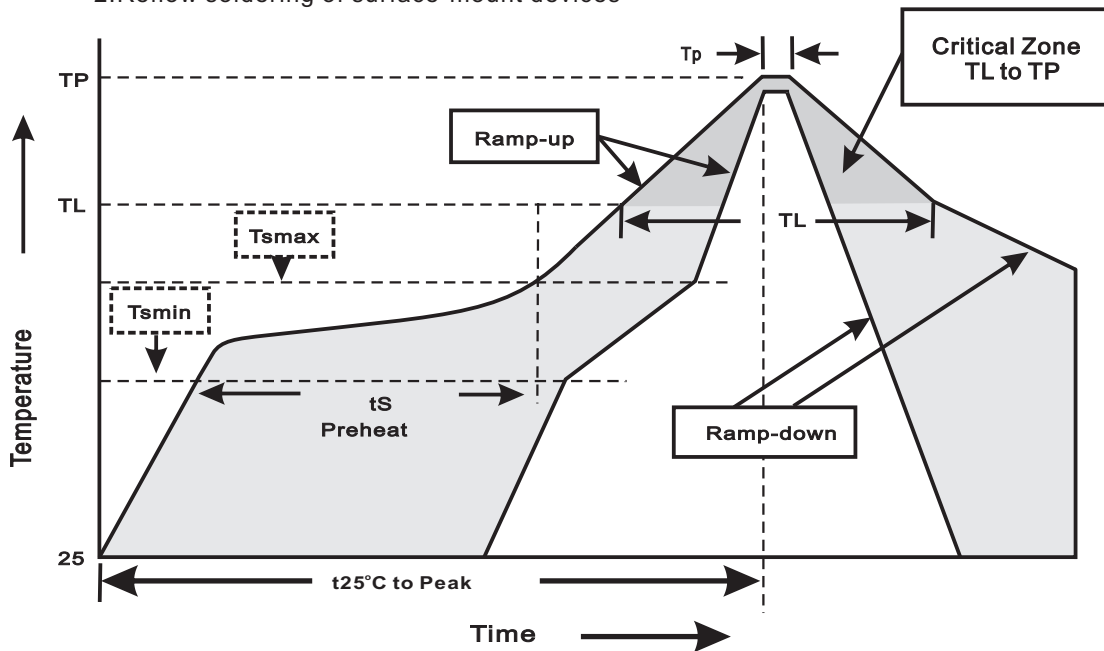
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## Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMB-S	13"	4,000	8.0	8,000	337*337*37	330	350*330*360	64,000	16.9

## Suggested thermal profiles for soldering processes

1. Storage environment: Temperature=5°C~40°C Humidity=55%±25%
2. Reflow soldering of surface-mount devices



### 3. Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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## High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at $260 \pm 5^\circ\text{C}$ for $10 \pm 2$ sec. immerse body into solder $1/16" \pm 1/32"$	MIL-STD-750D METHOD-2031
2. Solderability	at $245 \pm 5^\circ\text{C}$ for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R = 80\%$ rate at $T_J = 150^\circ\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at $T_A = 25^\circ\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^\circ\text{C}$ , $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	$15P_{SIG}$ at $T_A = 121^\circ\text{C}$ for 4 hrs.	JESD22-A102
7. Temperature Cycling	$-55^\circ\text{C}$ to $+125^\circ\text{C}$ dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Forward Surge	8.3ms single half sine-wave , one surge.	MIL-STD-750D METHOD-4066-2
9. Humidity	at $T_A = 85^\circ\text{C}$ , RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
10. High Temperature Storage Life	at $175^\circ\text{C}$ for 1000 hrs.	MIL-STD-750D METHOD-1031